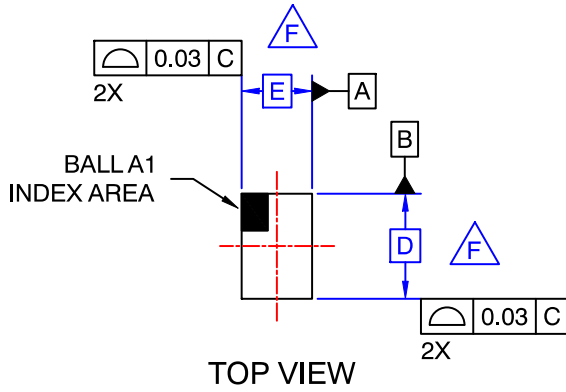
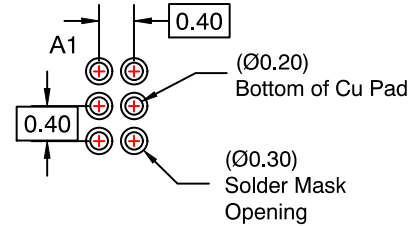


**WLCSP6 1.16x0.76x0.586**  
CASE 567RU  
ISSUE O

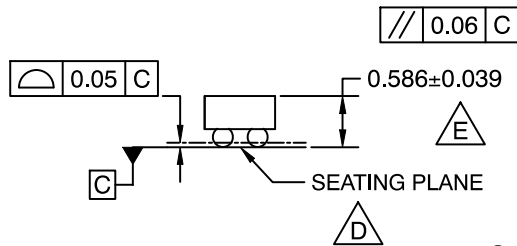
DATE 30 NOV 2016



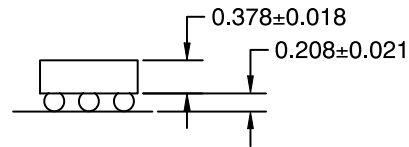
TOP VIEW



RECOMMENDED LAND PATTERN  
(NSMD PAD TYPE)

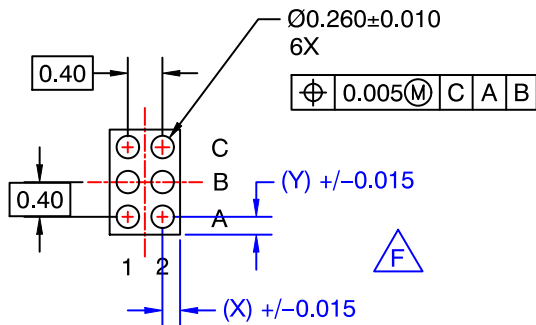


SIDE VIEWS



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASMEY14.5M, 2009.
- D. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 586 MICRONS ±39 MICRONS (547–625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y, SEE PRODUCT DATASHEET.



BOTTOM VIEW

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WLCSP6 1.16x0.76x0.586</b>	<b>PAGE 1 OF 2</b>

